FUJIFILM
Value from Innovation

ELECTRONIC MATERIALS

For an interconnect scaling, excellent planarity, and higher reliability

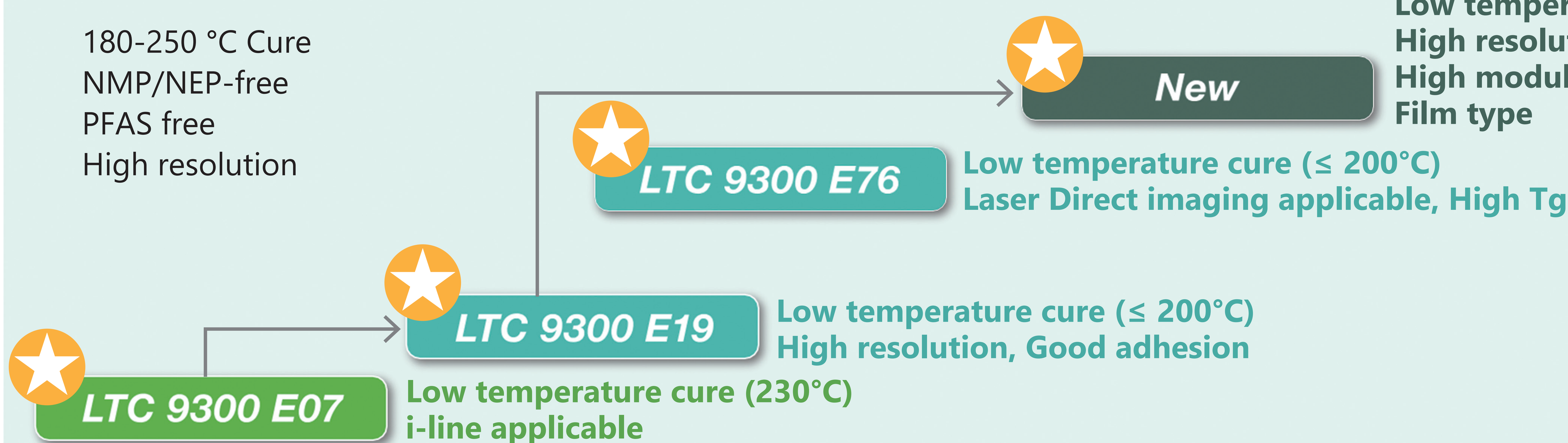
Photosensitive polyimide material ZEMATES™

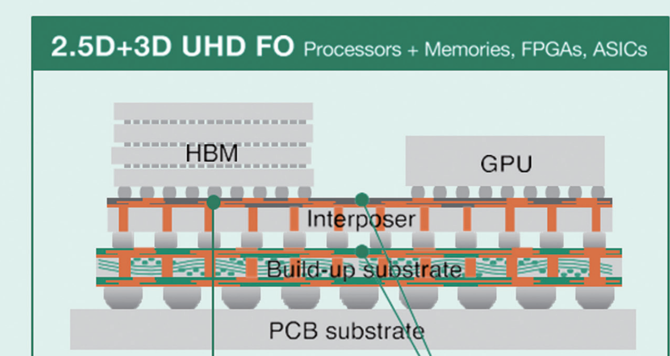
Be a trusted partner "MATES" driving innovation for our customers, supporting the future of the semiconductor industry together

Product roadmap (★ PFAS free)

Advanced RDL dielectric for WLP/PLP

180-250 °C Cure
NMP/NEP-free
PFAS free
High resolution

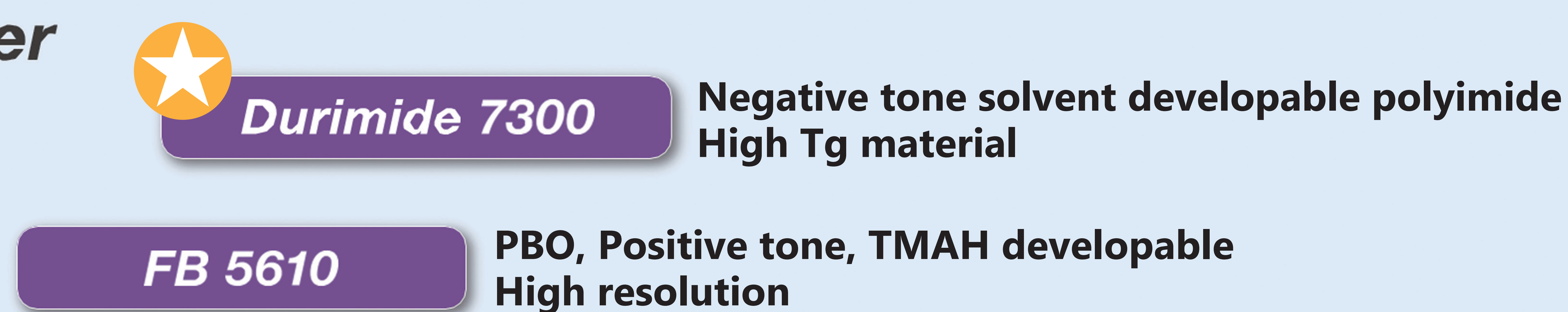




Liquid type polyimide
Film type polyimide

Advanced Buffer coat layer

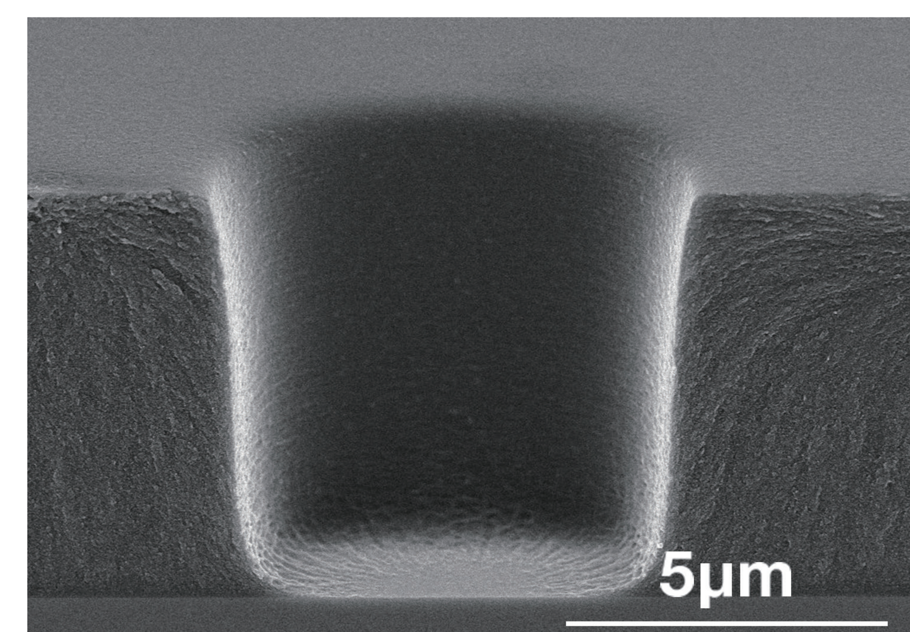
300-400 °C Cure
NMP/NEP



Liquid type polyimide

- A wide range of mechanical/thermal properties enable it to be applied to various RDL.
- Contributing to interconnect scaling with high resolution.
- Excellent reliability performance applicable to advanced packaging.

Ex) 5um Via 6.5um FT



Film type polyimide

- Multi-layered RDL is achievable with an excellent planarity by the vacuum laminating process.
- Applicable to a panel process enabling productivity improvements.
- Excellent reliability performance applicable to advanced packaging.

Ex) 7um Via 10um FT